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June 2013

FAN5340 PWM亮度控制并可断开负载的同步恒流升压串联LED驱动器

产品特性

- 同步电流模式升压变换器
- 输出功率可达500mW
- 支持2, 3, 或 4 个 LED 串联
- 输入电压范围: 2.7V-4.8V
- 1.2MHz 固定开关频率
- 1mA 最大静态电流
- 软启动
- 输入欠压锁定(UVLO)
- 输出过压保护 (OVP)
- 短路检测
- 热关闭保护() TSD
- 8-引脚, 3.00 x 3.00mm UMLP
- 8-引脚 (焊球), 1.57 x 1.57mm WLCSP

适用范围

- 手机,智能电话
- 便携式电脑
- WLAN DC-DC 变换器模块
- PDA、DSC、PMP 以及 MP3 播放器

说明

FAN5340 为同步恒流LED驱动器,可以向最多4个串联的LED提供最高可达500mW的功率。优化设计更适用于小型装置,1.2MHz的固定开关频率从而允许使用较小的芯片电感和电容

安全方面,器件整合了短路检测、过压和热关断保护功能。此外,若电池电压过低将触发输入欠压闭锁保护。

亮度(调光)控制通过在EN引脚上施加 300Hz 至 1kHz 的 PWM 信号来实现。关断期间,FAN5340 将 LED节点从保持升压稳压器电压Cour的升压稳压器输出端上断开,从而减少PWM调光的音频噪声,并断开 LED 串的电源。

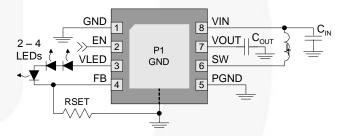


Figure 1. 典型应用

订购信息

器件型号	工作温度范围 對装		包装
FAN5340UCX	-40 至 +85°C	8 球型, 1.57 x 1.57mm 晶圆级芯片封装 (WLCSP)	卷带
FAN5340MPX (初级)	-40 至 +85°C	8-管脚, 3.00 x 3.00mm 超薄模塑无铅封装(MLP)	卷带

框图

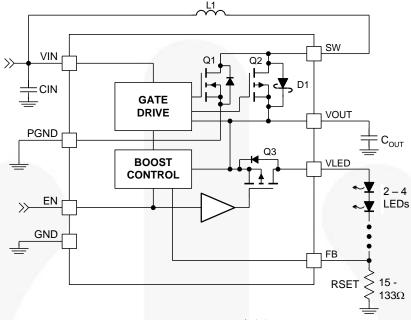


Figure 2. 框图

Table 1. 建议使用的外部器件

组件	说明	厂商	参数	最小值	典型值	最大值	单位
L1	22μH 标称	Murata	L ⁽¹⁾		22		μН
LI	22μΠ የአለሱ	LQH3NPN220MGOK	DCR (系列 R)		1100		mΩ
C _{OUT}	4.7μF X5R 或更好		С		4.7		μF
C _{IN}	4.7μF X5R 或更好		С		4.7		μF

说明:

1. 最小 L (电感) 涉及容限、温度和直流偏压的影响(L随电流升高而降低)。

引脚布局

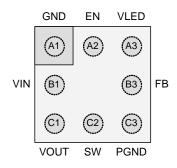


Figure 3. WLCSP 封装,顶视图

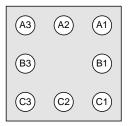


Figure 4. WLCSP 封装,底视图

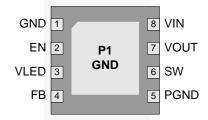


Figure 5. 8-引脚, 3 x 3mm 顶视图MLP,

引脚说明

引度	申号	名称	说明	
CSP	MLP		מי זע	
A1	1	GND	模拟地。所有信号均以该引脚为参照。	
A2	2	EN	用 / PWM亮度控制。该引脚上的逻辑低电平可关断芯片,将LED与 VOUT断开,并降低芯的功耗。该管脚上存在一只内部 300kΩ的下拉电阻。	
А3	3	VLED	ED串输出 。连接至两个至四个LED组成的串节点。	
В3	4	FB	!流反馈 。升压稳压器可将该引脚的电压调至0.5V,以控制LED的串行电流。将该引脚连接 ND和LED串阴极之间的电流设置电阻(R _{SET})。	
С3	5	PGND	源地 。升压开关和栅极驱动在此引脚接地。	
C2	6	SW	关节点 。电感L1连接在V _{IN} 和该引脚之间。	
C1	7	VOUT	十压输出电压 。升压稳压器的输出。	
B1	8	VIN	输入电压。	

绝对最大额定值

如果应力超过绝对最大额定值,器件就会毁损。在推荐的工作条件之上,该器件可能无法正常运行或操作,且不建议让器件在这些条件下长期工作。此外,过度暴露在高于推荐的工作条件下,会影响器件的可靠性。绝对最大额定值仅是额定应力值。

符号	参数		最小值	最大值	单位
V_{IN}	VIN		-0.3	6.0	V
V_{FB} , V_{EN}	FB、EN引脚		-0.3	V _{IN} + 0.3	V
V_{SW}	SW 引脚		-0.3	24.0	V
V _{OUT}	VOUT 引脚		-0.3	24.0	V
ESD	静电放电防护等级 人体模型满足JESD22-A114 充电器件模型满足JESD22-C101		4.0		kV
ESD			1.5		
TJ	结温		-40	+150	°C
T _{STG}	存储温度		-65	+150	°C
TL	引线焊接温度,10秒			+260	°C

推荐工作条件

推荐的操作条件表定义了真实器件的工作条件。指定推荐的工作条件,以确保设备的最佳性能达到数据表中的规格。飞兆半导体建议不要超过推荐工作条件,也不能按照绝对最大额定值进行设计。

符号	参数	最小值	典型值	最大值	单位
V _{IN}	VIN 电源电压	2.7	1	4.8	V
V _{OUT}	VOUT 电压	6.2		16.0	V
I _{OUT}	VOUT 负载电流	5		40	mA
f _{EN_PWM}	EN 引脚 PWM 调光频率		300	1000	Hz
T _A	环境温度	-40		+85	°C
TJ	结温	-40	A	+125	°C

热性能

结-环境之间热阻与具体应用和电路板布局有关。该数据由2s2p四层板测得,符合JESD51-JEDEC标准。特别注意的是,不要超过给定环境温度 T_A 时的结温 $T_{J(max)}$ 。

符号	参数		典型值	单位
0	结-环境之间热阻	WLCSP 封装	110	°C/W
$\theta_{\sf JA}$	与"机场之间然阻	MLP 封装	49	°C/W

电气规格

 V_{IN} = 2.7V 至 4.8V, T_A = -40°C至 +85°C,除非另有说明。典型值测量条件为 T_A = 25°C 且 V_{IN} = 3.6V。

符号	参数	工作条件	最小值	典型值	最大值	单位
电源	1		I.	'		
ΙQ	静态电流	EN = V _{IN} , 器件未开关			1	mA
I _{SD}	停机电源电流	EN = GND, V _{IN} = 3.6V		0.3	1.0	μΑ
W	石工學立	V _{IN} 升	2.30	2.40	2.50	V
V_{UVLO}	欠压锁定	V _{IN} 降	2.00	2.15	2.25	V
V _{UVHYST}	欠压锁定滞环宽度			250		mV
EN:启用引	脚					
V_{IH}	输入电压高电平		1.2			V
V_{IL}	输入电压低电平				0.4	V
R _{EN}	EN下拉电阻		200	300	400	kΩ
t _{SD}	EN 低电平,关断延迟	自 EN 的下降沿	20		80	ms
反馈和参考						
V_{FB}	反馈电压		480	500	520	mV
I _{FB}	反馈输入电流	V _{FB} = 500mV		0.1	1.0	μΑ
电源输出					7	
Page 10	升压开关接通电阻	$V_{IN} = 3.6V, V_{OUT} = 10V, I_{SW} = 100 mA$		600		m()
R _{DS(ON)_Q1}		$V_{IN} = 2.7V, V_{OUT} = 10V, I_{SW} = 100mA$		850		mΩ
$R_{DS(ON)_Q2}$	同步整流导通电阻	V _{OUT} = 10V, I _{SW} = 100mA		2.0		Ω
R _{DS(ON)_Q3}	负载开关导通电阻	$V_{OUT} = 10V$, $I_{LED} = 10mA$		2.8		Ω
I _{SW(OFF)}	SW 节点漏电流 ⁽²⁾	$EN = 0$, $V_{IN} = V_{SW} = V_{OUT} = 5.5V$, $V_{LED} = 0$		0.1	1.0	μА
I _{LIM-PK}	升压开关峰值电流限值	$V_{IN} = 3.6V$	325	400	475	mA
振荡器			- //			
f _{SW}	升压稳压器开关频率		1.0	1.2	1.4	MHz
PWM 调光		•	/			
D_PWM	PWM 占空比 ⁽³⁾	PWM调光频率≤1kHz	1.0		100	%
输出和保护	1					
V _{OVP}	升压输出过压保护 (OVP)		18.0	19.0	20.0	V
V _{OVPHYST}	OVP 滞环			0.8		V
V_{THSC}	V _{LED} 短路检测阈值	V _{OUT} 降		V _{IN} – 1.5		V
11100		V _{оит} 升		V _{IN} – 1.3		V
D _{MAX}	最大升压占空比(3)		85			%
D _{MIN}	最小升压占空比 ⁽³⁾				20	%
T _{SD}	热关闭			150		°C
T_{HYS}	热关闭滞环宽度			25		°C

说明:

- 2. SW 漏电流包括三个内部开关的漏电流; SW 至 GND, Vout 至 VLED, 以及 SW 至 Vout.
- 3. 设计保证。

典型特性

 $V_{IN} = 3.6 V$, $T_A = 25 ^{\circ} C$, $I_{LED} = 20 mA$, $L = 22 \mu H$, $C_{OUT} = 4.7 \mu F$.

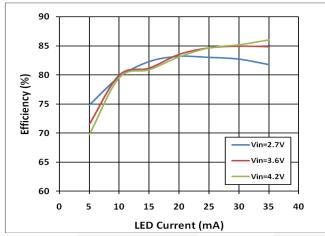


Figure 6. 效率 vs. LED 电流: 2 LED

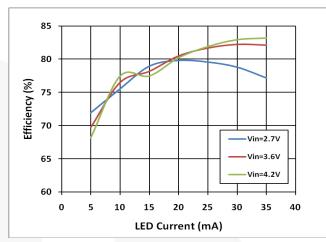


Figure 7. 效率 vs. LED 电流: 3 LED

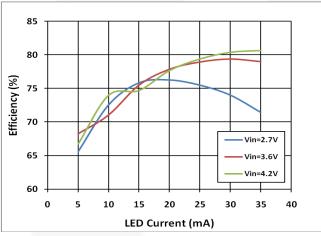


Figure 8. 效率 vs. LED 电流: 4 LED

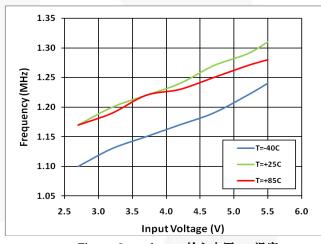


Figure 9. f_{sw} vs.输入电压 vs.温度

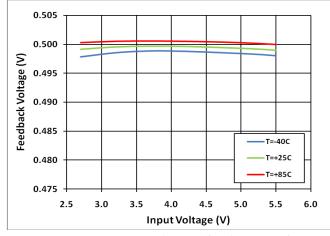


Figure 10. FB 电压 vs.输入电压 vs.温度

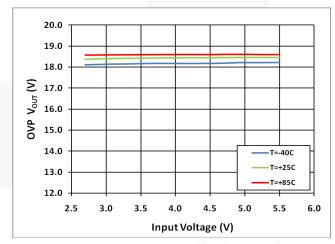


Figure 11. OVP vs.输入电压vs.温度

典型特性(续)

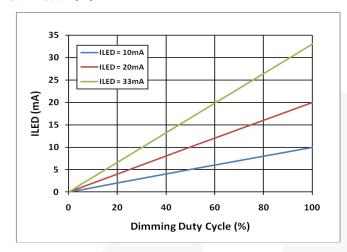


Figure 12. PWM 线性化,超过调光占空比全程,4 LED

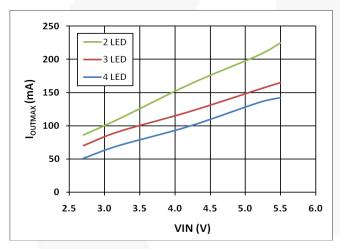


Figure 14. VouT上的最大输出电流

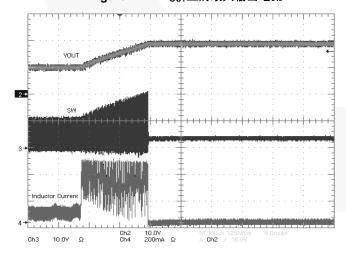


Figure 16. 过压保护: 软起动,打开LED串

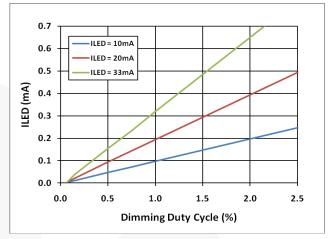


Figure 13. PWM 线性化,调光占空比<2.5%,4 LED

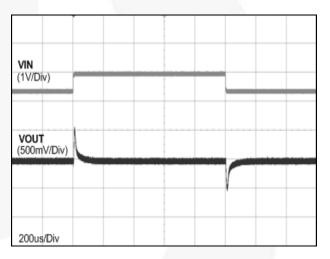


Figure 15. 电源瞬态,步进10µs 4 LED

典型特性(续)

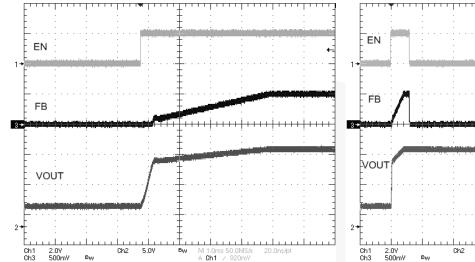
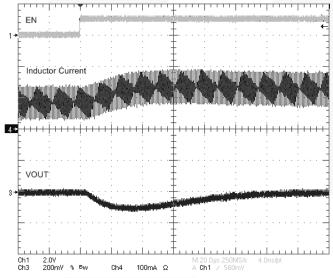


Figure 17. 1ms/Div, 100%占空比的冷启动波形

Figure 18. 100%占空比的冷启动波形以10ms/Div显示 启动、关断再启动。

ΕN



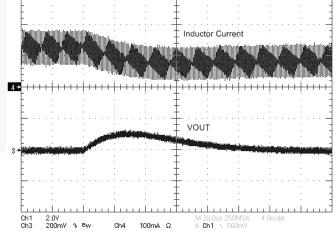


Figure 19. FAN5340 I_{LOAD} 从 20mA 步进至 30mA,通过在10mA 启用 FAN5640 3 LED

Figure 20. FAN5340 I_{LOAD} 从 30mA 步进至 20mA, 通过在10mA 禁用 FAN5640 3 LED

电路说明

概述

FAN5340 是一款电感电流模式升压的串联 LED 驱动器,通过保持 R_{SET} 电阻 0.5V 的电压实现LED电流的调节。LED 串的电流(I_{LED})的计算公式为:

$$I_{LED} = \frac{0.5}{R_{SET}} \tag{1}$$

LED上的正向电压可决定 V_{OUT},FAN5340 的升压稳压器输出 也可以支持V_{OUT} (参见图 21) 上的其他负载,前提是不超过输入电流限制。

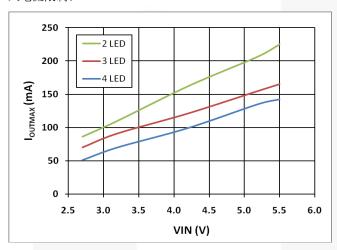


Figure 21. 最大输出电流 vs. 输入电压

UVLO 和软启动

若 EN 低电平超过 20ms, 芯片在EN 升高时将进行"冷启动"的 软起动周期, 前提是 V_{IN} 超过 UVLO 阈值。软起动电路将参考电压输入误差放大器,从而控制冲击电流。

PWM 调光

EN 低电平时,芯片关断一个 MOSFET (Q3 图2), 其断开 LED 负载,防止EN引脚低电平时 Cout 放电。只要 EN 低电平的时间不超过 20ms,稳压器的主回路将在 EN 恢复高电平时迅速恢复控制。

短路检测

 V_{OUT} 降至 V_{IN} – 1.5V 以下时,Q3 关断直至 V_{OUT} 至少恢复至 V_{IN} – 1.3V 方可导通。

过压保护

若 LED 串采用开路, FB 保持为 0V, 且输出电压在没有过压保护(OVP)电路的情况下持续升高。当 Vour 超过19.0V时, FAN5340的 OVP电路将禁用升压稳压器,并持续到Vour降至18.2V以下方可启用。

热关闭

晶圆温度超过150°C时,发生复位并保持,直至晶圆冷却至125°C:此时允许电路开始软起动序列。

适用范围

使用 VOUT 驱动附加的 LED 串

VOUT 引脚可用作简单电流源(如图22使用FAN5640所示)或分离电流槽。为避免 EN 引脚在低电平时下拉 V_{OUT},应启用辅助串,除非 EN 引脚处于高电平。因而辅助串可使用与EN 相同线路进行 PWM 调光,如图所示,或单独启用,但应在 FAN5340 的导通期间。

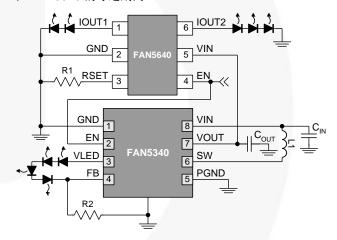
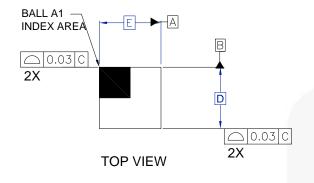
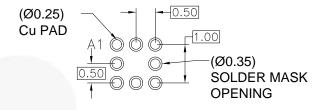


Figure 22. 驱动附加的 LED 串

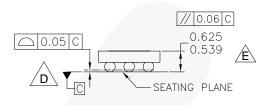
若使用 VOUT 驱动附加负载,应注意不要超过输入电流限制。图21 给出了典型芯片的限制。总负载(lour1 + lour2 + lled) 应保持低于图21值的 70%。

物理尺寸





RECOMMENDED LAND PATTERN (NSMD)



(X)+/-.018

B-(Y)+/-.018

⊕ Ø0.005(M) C A B

8 X Ø0.315 +/- .025



SIDE VIEWS

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C, DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- PACKAGE TYPICAL HEIGHT IS 582 MICRONS ± 43 MICRONS (539-625 MICRONS).



- G. BALL COMPOSITION: Sn95.5-Ag3.9-Cu0.6
- I. DRAWING FILENAME: MKT-UC008ABrev2.

产品规格尺寸

0.50

0.50

2 3

BOTTOM VIEW

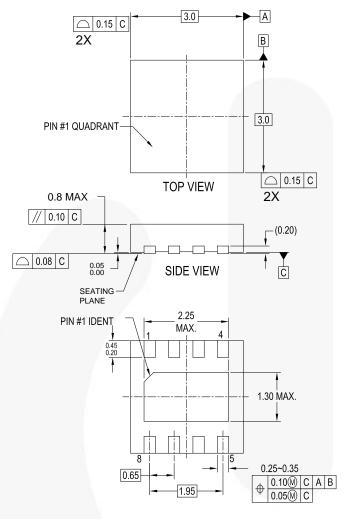
产品	D	E	Х	Y
FAN5340UC	1.570	1.570	0.285	0.285

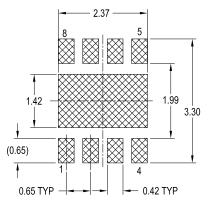
Figure 23. 8 球型, 1.57 x 1.57mm 晶圆级芯片封装(WLCSP)

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A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VEEC, DATED 11/2001

- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. FILENAME: MKT-MLP08Drev2

Figure 24. 8-管脚, 3 x 3mm 超薄模塑无铅封装(MLP)

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